

## **HAT2132H**

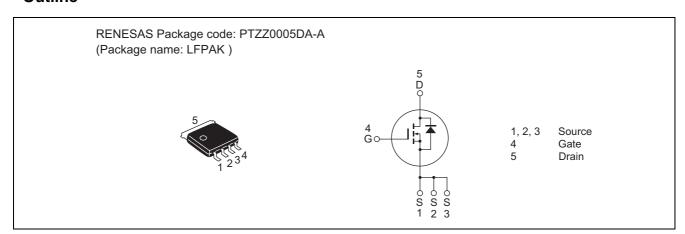
# Silicon N Channel MOS FET High Speed Power Switching

REJ03G0177-0300 Rev.3.00 Dec 07, 2006

### **Features**

- Low drive current.
- Low on-resistance
- Low profile

### **Outline**



### **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Ratings	Unit
Drain to source voltage	V <sub>DSS</sub>	200	V
Gate to source voltage	V <sub>GSS</sub>	±30	V
Drain current	I <sub>D</sub>	6	Α
Drain peak current	I <sub>D(pulse)</sub> Note1	24	Α
Body-drain diode reverse drain current	I <sub>DR</sub>	6	Α
Body-drain diode reverse drain peak current	I <sub>DR(pulse)</sub> Note1	24	Α
Avalanche current	I <sub>AP</sub> Note3	6	Α
Avalanche energy	E <sub>AR</sub> Note3	2.4	mJ
Channel dissipation	Pch Note2	20	W
Channel to case thermal impedance	θch-c	6.25	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW  $\leq$  10  $\mu$ s, duty cycle  $\leq$  1%

2. Value at  $Tc = 25^{\circ}C$ 

3. STch =  $25^{\circ}$ C, Tch  $\leq 150^{\circ}$ C

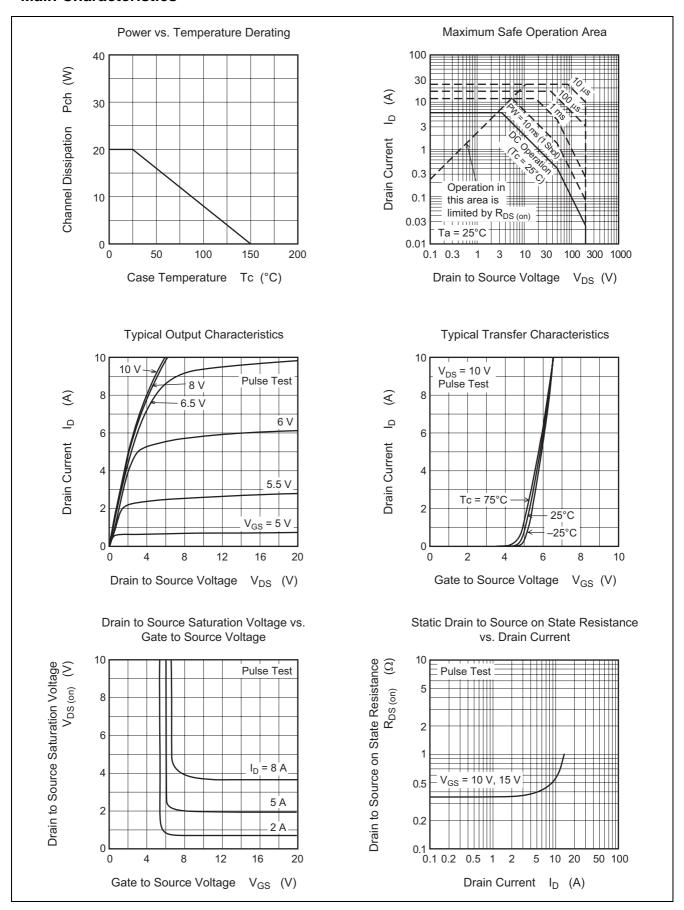
### **Electrical Characteristics**

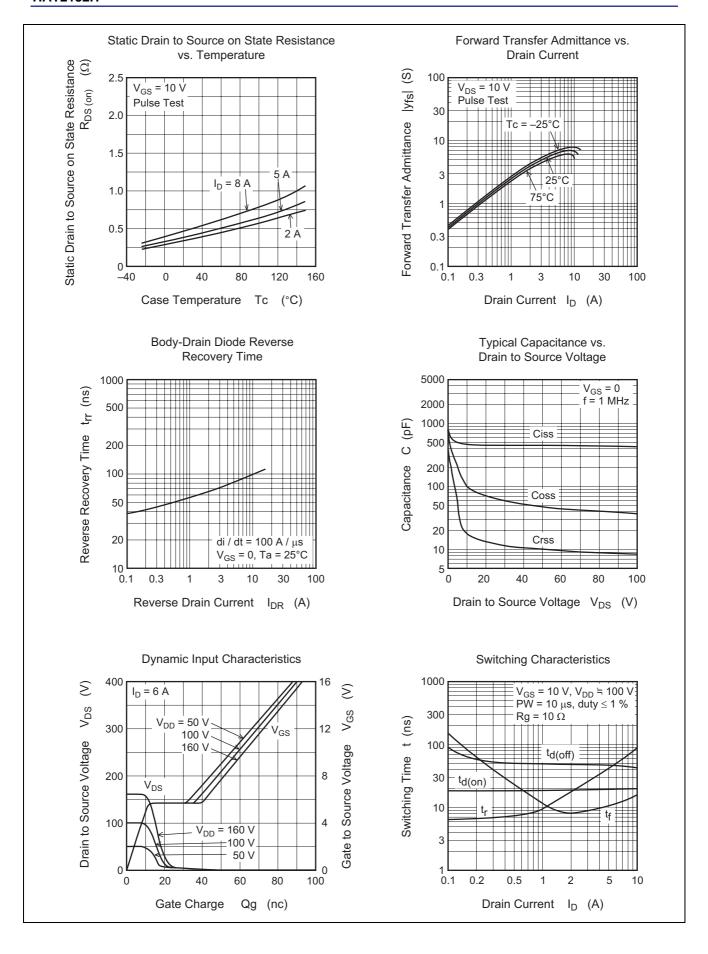
 $(Ta = 25^{\circ}C)$ 

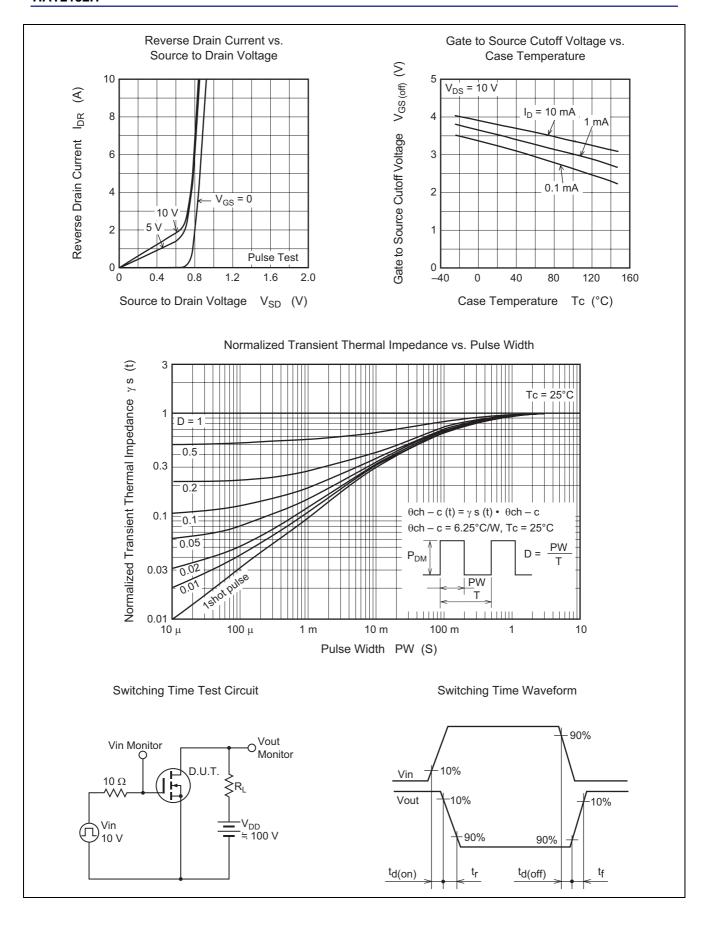
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	200	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 200 \text{ V}, V_{GS} = 0$
Gate to source leak current	I <sub>GSS</sub>	_	_	±0.1	μΑ	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	3.0	_	4.0	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Forward transfer admittance	y <sub>fs</sub>	2.7	4.7	_	S	$I_D = 3 \text{ A}, V_{DS} = 10 \text{ V}^{Note4}$
Static drain to source on state resistance	R <sub>DS(on)</sub>	_	0.36	0.45	Ω	$I_D = 3 \text{ A}, V_{GS} = 10 \text{ V}^{Note4}$
Input capacitance	Ciss	_	450	_	pF	V <sub>DS</sub> = 25 V
Output capacitance	Coss	_	65	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	13	_	pF	f = 1 MHz
Turn-on delay time	t <sub>d(on)</sub>	_	19	_	ns	I <sub>D</sub> = 3 A
Rise time	t <sub>r</sub>	_	26	_	ns	V <sub>GS</sub> = 10 V
Turn-off delay time	t <sub>d(off)</sub>	_	48	_	ns	$R_L = 33.3 \Omega$
Fall time	t <sub>f</sub>	_	9	_	ns	$Rg = 10 \Omega$
Total gate charge	Qg	_	12.5	_	nC	V <sub>DD</sub> = 160 V
Gate to source charge	Qgs	_	2.5	_	nC	V <sub>GS</sub> = 10 V
Gate to drain charge	Qgd	_	6	_	nC	$I_D = 6 A$
Body-drain diode forward voltage	$V_{DF}$	_	0.85	1.30	V	$I_F = 6 \text{ A}, V_{GS} = 0$ Note4
Body-drain diode reverse recovery time	t <sub>rr</sub>	_	95	_	ns	$I_F = 6 \text{ A}, V_{GS} = 0$
						di <sub>F</sub> /dt = 100 A/μs

Notes: 4. Pulse test

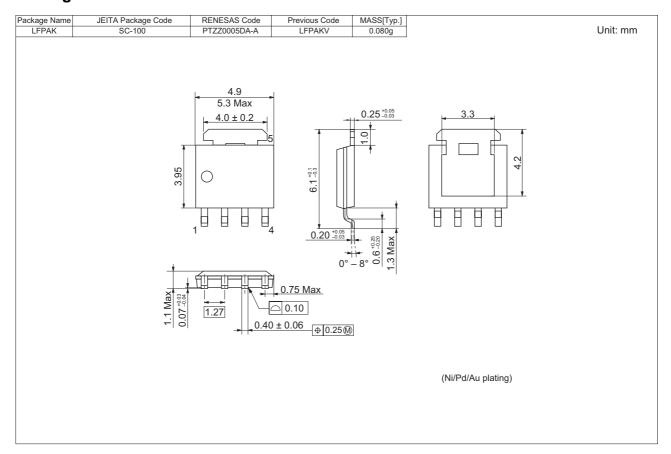
### **Main Characteristics**







### **Package Dimensions**



### **Ordering Information**

Part No.	Quantity	Shipping Container
HAT2132H-EL-E	2500 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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